

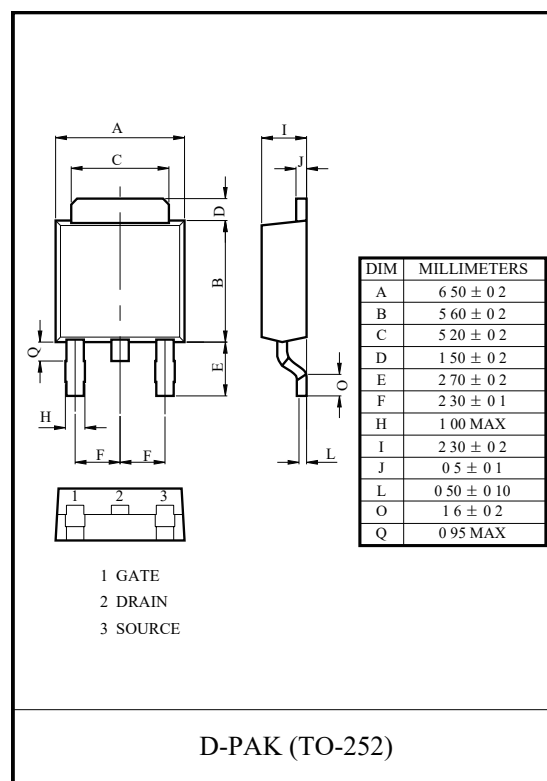
N-Channel Power MOSFET

GENERAL DESCRIPTION

The FTK50N06D uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

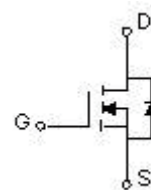
FEATURE

- High density cell design for ultra low R_{dson}
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability



APPLICATION

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Symbol	Parameter		Max.	Units
V _{DSS}	Drain-Source Voltage		60	V
V _{GSS}	Gate-Source Voltage		±20	V
I _D	Continuous Drain Current	T _C = 25 °C	50	A
		T _C = 100 °C	33	A
I _{DM}	Pulsed Drain Current ^{note1}		200	A
E _{AS}	Single Pulsed Avalanche Energy ^{note2}		64	mJ
P _D	Power Dissipation	T _C = 25 °C	89	W
R _{θJC}	Thermal Resistance, Junction to Case		1.69	°C/W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250μA	60	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =60V, V _{GS} =0V,	-	-	1.0	μA
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.0	1.6	2.5	V
R _{DS(on)}	Static Drain-Source on-Resistance note3	V _{GS} =10V, I _D =30A	-	12	17	mΩ
		V _{GS} =4.5V, I _D =20A	-	16	25	
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1.0MHz	-	2900	-	pF
C _{oss}	Output Capacitance		-	140	-	pF
C _{rss}	Reverse Transfer Capacitance		-	120	-	pF
Q _g	Total Gate Charge	V _{DS} =30V, I _D =30A, V _{GS} =10V	-	50	-	nC
Q _{gs}	Gate-Source Charge		-	6	-	nC
Q _{gd}	Gate-Drain(“Miller”) Charge		-	15	-	nC
Switching Characteristics						
t _{d(on)}	Turn-on Delay Time	V _{DS} =30V, I _D =30A, R _G =1.8Ω, V _{GS} =10V	-	7.4	-	ns
t _r	Turn-on Rise Time		-	5.1	-	ns
t _{d(off)}	Turn-off Delay Time		-	28.2	-	ns
t _f	Turn-off Fall Time		-	5.5	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	50	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	200	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S =30A	-	-	1.2	V
t _{rr}	Body Diode Reverse Recovery Time	I _F =30A, dI/dt=100A/μs	-	28	-	ns
Q _{rr}	Body Diode Reverse Recovery Charge		-	40	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition : $T_J=25^\circ\text{C}, V_{DD}=30V, V_G=10V, L=0.5mH, R_g=25\Omega, I_{AS}=16A$

3. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure1: Output Characteristics

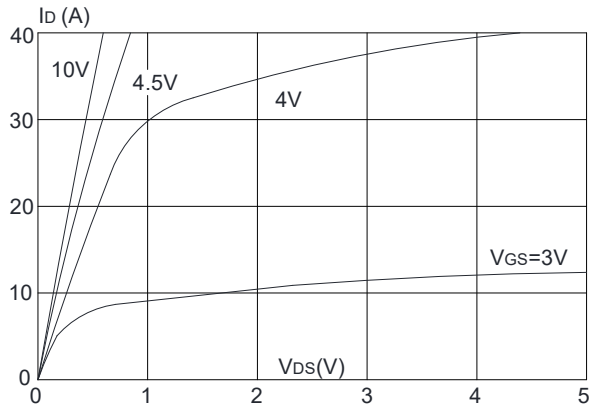


Figure 2: Typical Transfer Characteristics

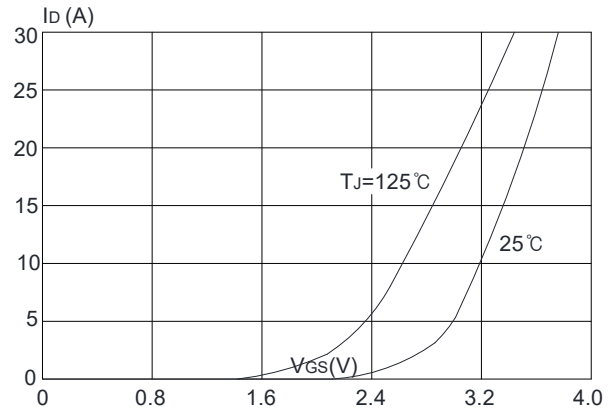


Figure 3: On-resistance vs. Drain Current

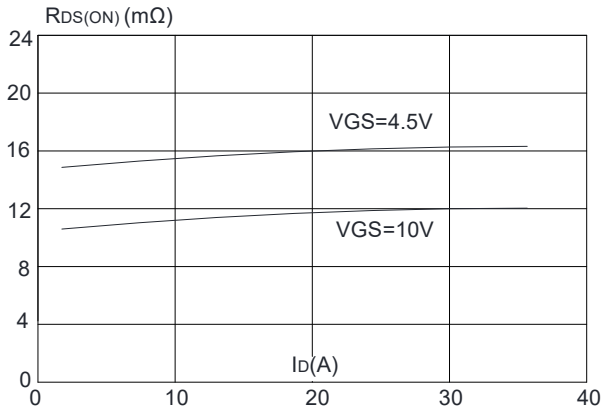


Figure 4: Body Diode Characteristics

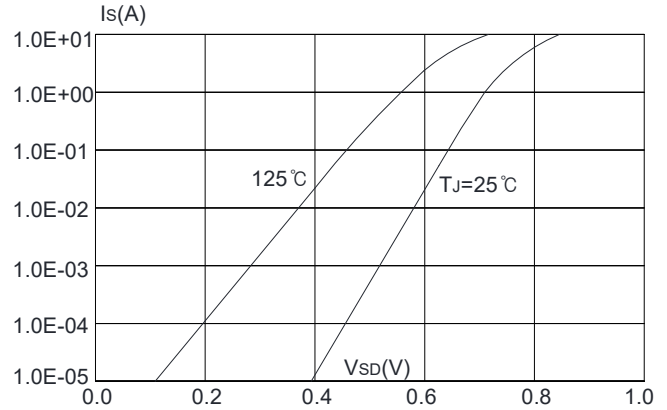


Figure 5: Gate Charge Characteristics

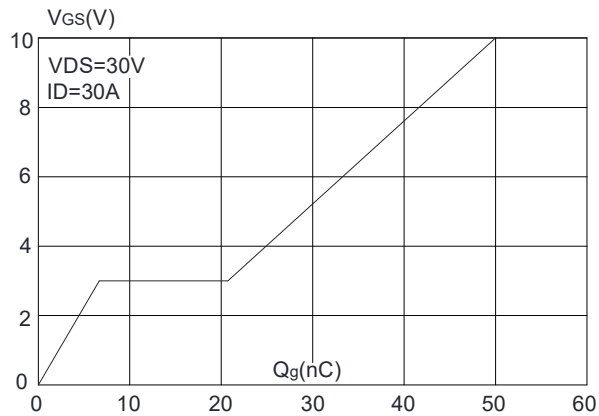


Figure 6: Capacitance Characteristics

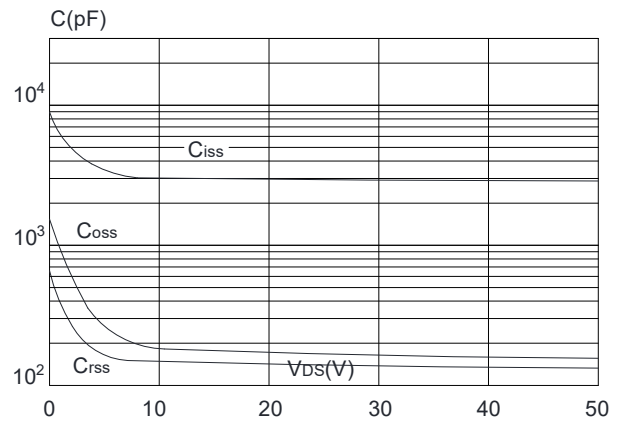


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

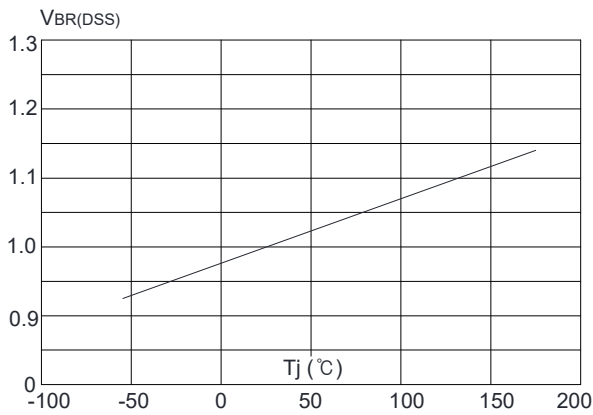


Figure 8: Normalized on Resistance vs. Junction Temperature

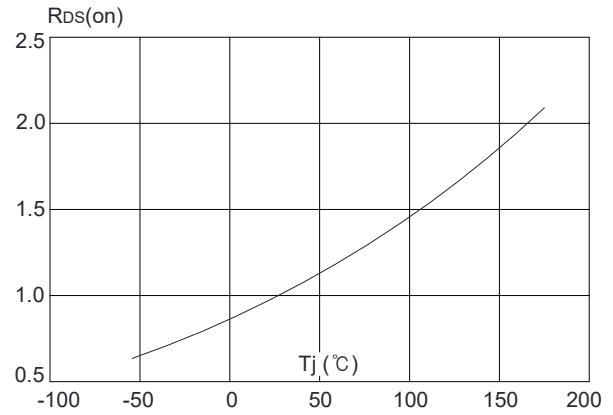


Figure 9: Maximum Safe Operating Area

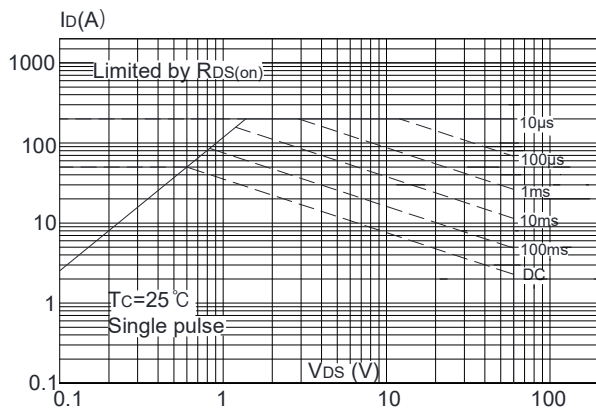


Figure 10: Maximum Continuous Drain Current vs. Case Temperature

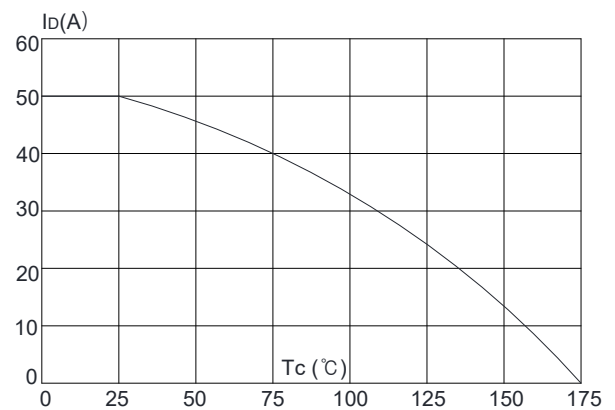


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Case

